

ABSTRACT**METHOD FOR LOW TEMPERATURE LAMINATION OF METALS TO
FLUOROPOLYMERS**

The present invention is directed to a method for the lamination of metals, and especially copper, to the surfaces of fluoropolymers at temperatures substantially below the sintering temperatures or melting temperatures of the fluoropolymers. More specifically, the invention is directed to a method for surface modification of fluoropolymers by thermal graft copolymerization with concurrent lamination of a metal (e.g. copper) in the presence of a functional monomer. The process can be carried out under atmospheric conditions and in the complete absence of an added polymerization initiator. The so-laminated fluoropolymer-metal interfaces exhibit T-peel strengths of no less than 8 N/cm and delaminate via cohesive failure inside the fluoropolymer.